



Material Content Data Sheet



Sales Product Name				IDH08S120		Issued		19. July 2018	
MA#				MA000623046					
Package				PG-TO220-2-1		Weight*		1970.59 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.556	0.18	0.18	1804	1804	
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		382		
	inorganic material	phosphorus	7723-14-0	0.226	0.01		115		
	non noble metal	copper	7440-50-8	751.797	38.15	38.20	381509	382007	
wire	non noble metal	aluminium	7429-90-5	0.639	0.03	0.03	324	324	
encapsulation	organic material	carbon black	1333-86-4	9.055	0.46		4595		
	plastics	epoxy resin	-	99.609	5.05		50548		
	inorganic material	silicondioxide	60676-86-0	495.026	25.12	30.63	251208	306351	
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7351	7351	
plating	non noble metal	nickel	7440-02-0	0.198	0.01		100		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	1	100	
solder	noble metal	silver	7440-22-4	0.125	0.01		64		
	non noble metal	tin	7440-31-5	0.100	0.01		51		
	non noble metal	lead	7439-92-1	4.781	0.24	0.26	2426	2541	
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		300		
	inorganic material	phosphorus	7723-14-0	0.177	0.01		90		
	non noble metal	copper	7440-50-8	589.466	29.91	29.95	299132	299522	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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